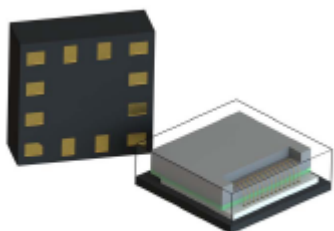


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## Ultra-compact two-axis gyroscope for optical image stabilization



LGA-12 (2.0 x 2.0 x 0.7 mm)

### Features

- Two selectable full scales (625/2500 dps)
- Embedded self-test
- Wide supply voltage range: 2.4 V to 3.6 V
- Embedded power-down and sleep mode
- Embedded low-pass filter
- Integrated high-pass filter reset
- High shock survivability
- Extended operating temperature range (-40 °C to 85 °C)
- ECOPACK® RoHS and “Green” compliant

### Description

The device is a low-power three-axis angular rate sensor.

It includes a sensing element and an IC interface capable of providing the measured angular rate to the external world via three analog outputs.

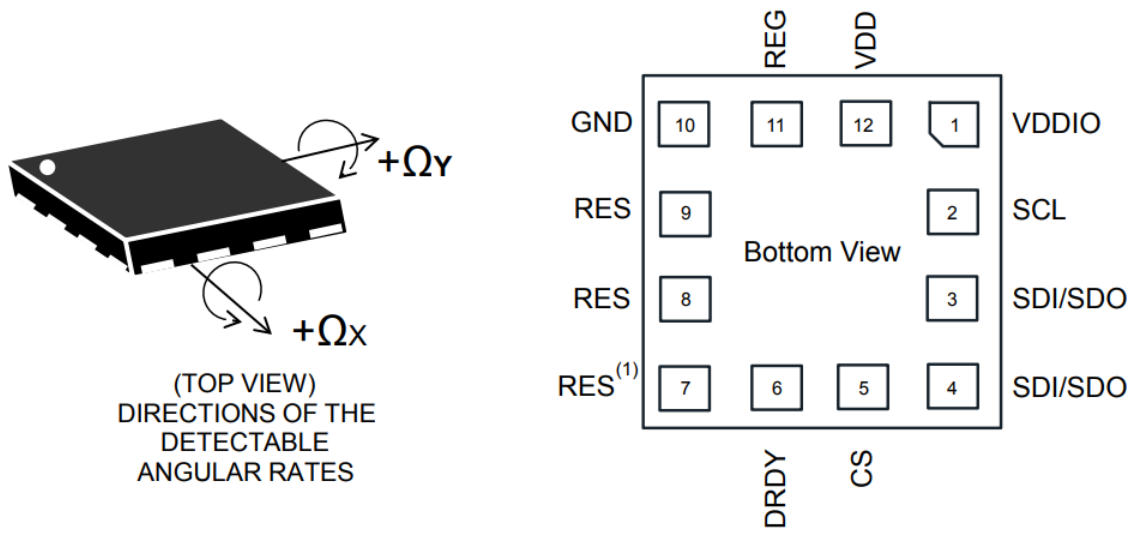
The sensing element is manufactured using a dedicated micro-machining process developed by STMicroelectronics to produce inertial sensors and actuators on silicon wafers.

The IC interface is manufactured using a CMOS process that allows a high level of integration to design a dedicated circuit which is trimmed to better match the sensing element characteristics.

The device is available in a plastic land grid array (LGA) package and can operate within a temperature range from -40 °C to +85 °C.

# 1 PIN Connection

Figure 1. PIN Connection



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**Figure 2. PIN Connection**

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**Table 1.**

(1)			

1.

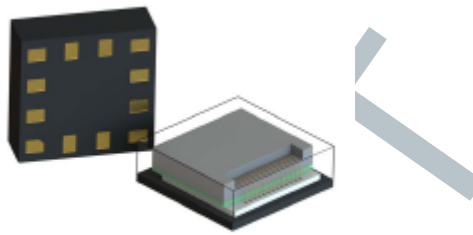
<b>Principles</b>	<b>Weeks 11-12</b>
<b>for assignment</b>	<b>March 11th-March 24</b>
Events	APEC <sup>(1)</sup>
Japanese alternative	Industrial applications (JP)
Chinese alternative	Electronica China (ZH)

1. *tradeshow*

## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 LGA-12 (2.0 x 2.0 x 0.7 mm) package silhouette



LGA-12 (2.0 x 2.0 x 0.7 mm)

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## Revision history

**Table 2. Document revision history**

Date	Version	Changes
23-04-2019	1	Initial release.

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